

LM6511 180 ns 3V Comparator

Check for Samples: LM6511

FEATURES

- (Typical Unless Otherwise Noted)
- Operates at +2.7V, +3V, +3.3V, +5V
- Low Power Consumption <9.45 mW @ V⁺ = 2.7V (max)
- Fast Response Time of 180 ns

APPLICATIONS

- Portable Equipment
- Cellular Phones
- · Digital Level Shifting

DESCRIPTION

The LM6511 voltage comparator is ideal for analog-digital interface circuitry when only a +3V or +3.3V supply is available. The open-collector output permits signal compatibility with a wide variety of digital families: +5V CMOS, +3V CMOS, TTL and so on. Supply voltage may range from 2.7V to 36V between supply voltage leads. The LM6511 operates with little power consumption (P_{diss} < 9.45 mW at V⁺ = +2.7V and V⁻ = 0V).

This voltage comparator offers many features that are available in traditional sub-microsecond comparators: output sync strobe, inputs and output may be isolated from system ground, and wire-ORing. Also, the LM6511 uses the industry-standard, single comparator pinout configuration.

Connection Diagram

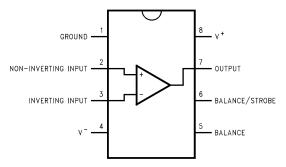


Figure 1. 8-Pin SOIC See Package Number D



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.



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Absolute Maximum Ratings (1)(2)

| Supply Voltage | | -0.3 to +36V |
|---|--------------------------------------|--------------------|
| Output to Negative Supply Voltage | | 50V |
| Ground to Negative Supply Voltage | | 30V |
| Differential Input Voltage | | ±30V |
| Input Voltage | | See ⁽¹⁾ |
| Storage Temperature Range | | -65°C to +150°C |
| Soldering Information: | SOIC Package (Vapor Phase in 60 sec) | 215°C |
| | SOIC Package (Infrared in 15 sec) | 220°C |
| Power Dissipation | | 500 mW |
| Output Short Circuit Duration | | 10s |
| Junction Temperature | | 150°C |
| ESD Rating (C = +100 pF, R = 1.5 k Ω) | | 300V |

⁽¹⁾ Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating ratings indicate conditions the device is intended to be functional, but do not guarantee specific performance limits. For guaranteed specifications and test conditions, see the Electrical Characteristics. The guaranteed specifications apply only for the test conditions listed.

Operating Ratings⁽¹⁾

| Supply Voltage | | 2.5V to 30V |
|---------------------------------------|--------------|-----------------------------------|
| Temperature Range | | -40°C ≤ T _J ≤ $+85$ °C |
| Thermal Resistance (θ _{JA}) | SOIC Package | 170°C/W |

⁽¹⁾ Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating ratings indicate conditions the device is intended to be functional, but do not guarantee specific performance limits. For guaranteed specifications and test conditions, see the Electrical Characteristics. The guaranteed specifications apply only for the test conditions listed.

DC Electrical Characteristics

Unless otherwise specified, all limits guaranteed for $T_J = 25^{\circ}\text{C}$. **Boldface** limits apply at the temperature extremes. $V^+ = 2.7V$, $V^- = 0V$, $50\Omega \le R_1 \le 50k\Omega$, and $I_1 = 1.0$ mA unless otherwise specified

| Symbol | Parameter | Conditions | Typical | LM6511I | Units | |
|---------------------|-----------------------------|------------------------------------|---------|---------|-----------|--|
| | | | | Limit | (Limits) | |
| V _{OS} | Offset Voltage | $R_S \le 50 \text{ k}\Omega^{(1)}$ | 1.5 | 5 | mV | |
| | | | | 8 | max | |
| I _B | Input Bias Current | | 38 | 130 | nA | |
| | | | | 200 | max | |
| Ios | Input Offset Current | $R_S \le 50 \text{ k}\Omega^{(1)}$ | 1.5 | 20 | nA | |
| | | | | 50 | max | |
| I _S | Positive Supply Current | | 2.7 | 3.5 | | |
| | | | | 5 | mA | |
| | Negative Supply Current | | 1.5 | 2.0 | max | |
| | | | | 2.5 | | |
| V _{SAT} | Saturation Voltage | V _{IN} ≤ 10 mV | 0.23 | 0.4 | V | |
| | | I _{SINK} = 8 mA | | 0.4 | max | |
| A _V | Large Signal Voltage Gain | $\Delta V_{OUT} = 2V$ | 40 | | V/mV | |
| CMRR | Common Mode Rejection Ratio | | 72 | | dB | |
| I _{STROBE} | Strobe ON Current | See ⁽²⁾ | 2.0 | 5.0 | mA max | |

⁽¹⁾ The offset voltage and offset current limits are the maximum values required to drive the output within a volt of either supply with a 1 mA load. Therefore, these parameters define an error band and take into account the worst-case effects of voltage gain and input impedance.

Product Folder Links: LM6511

⁽²⁾ If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/ Distributors for availability and specifications.

⁽²⁾ This specification gives the range of current which must be drawn from the strobe pin to ensure the output is properly disabled. Do not short the strobe pin to ground; it should be current driven at 3 mA to 5 mA.



DC Electrical Characteristics (continued)

Unless otherwise specified, all limits guaranteed for T_J = 25°C. **Boldface** limits apply at the temperature extremes. V^+ = 2.7V, V^- = 0V, $50\Omega \le R_L \le 50k\Omega$, and I_L = 1.0 mA unless otherwise specified

| Symbol | Parameter | Conditions | Typical | LM6511I | Units |
|-----------------|------------------------|--|---------|-----------------------|-----------|
| | | | | Limit | (Limits) |
| V _{IN} | Input Voltage Range | | | 0.50 | V min |
| | | | | V ⁺ - 1.25 | V max |
| | Output Leakage Current | $V_{IN} \ge 10 \text{ mV}, V_{OUT} = 35\text{V},$ $I_{STROBE} = 3 \text{ mA}$ | 0.2 | | nA max |

AC Electrical Characteristics

Unless otherwise specified, all limits guaranteed for $T_J = 25^{\circ}C$. **Boldface** limits apply at the temperature extremes. $V^+ = 2.7V$, $V^- = 0V$, $50\Omega \le R_L \le 50k\Omega$, and $I_L = 1.0$ mA unless otherwise specified

| Symbol | Parameter | Conditions | Typical | LM6511I | Units | |
|----------------|---------------|--------------------|---------|---------|----------|--|
| | | | | Limit | (Limits) | |
| T _R | Response Time | See ⁽¹⁾ | 180 | | ns | |

(1) This specification is for a 100 mV input step with a 25 mV overdrive.

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LM6511 Typical Performance Characteristics

 $V_S = 3V$ unless otherwise noted

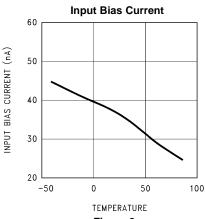


Figure 2.

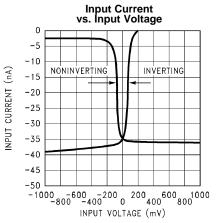
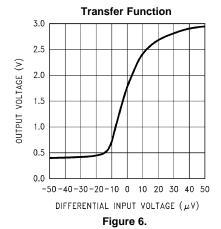
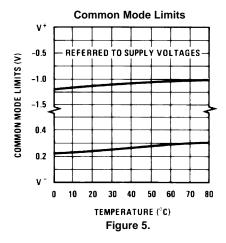


Figure 4.



TEMPERATURE **Figure 3.**



Output Saturation Voltage

0.35

0.3

0.3

| OUT = 8 mA | OUT = 8 mA |

0.15

0.15

0.1

-50

0 50

TEMPERATURE

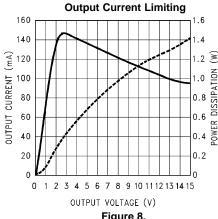
Figure 7.

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LM6511 Typical Performance Characteristics (continued)

 $V_S = 3V$ unless otherwise noted







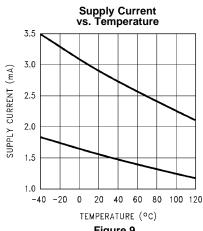


Figure 9.

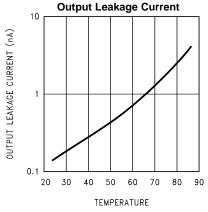
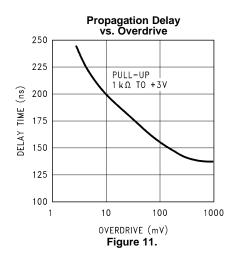
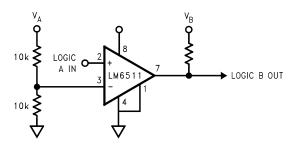


Figure 10.



Typical Application

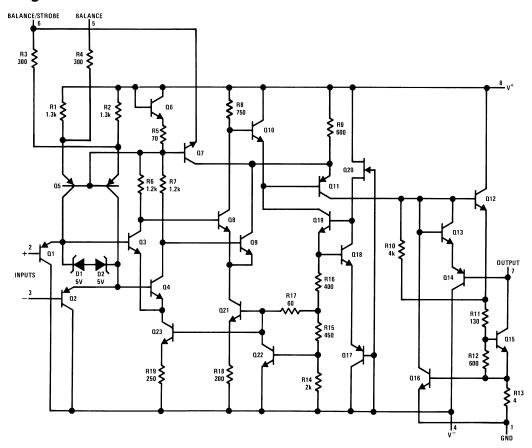


Notes: Because of the very wide operating and output voltage range, the LM6511 may be used to shift logic levels from 3V to TTL or CMOS to the other way around. By biasing the input to ½ of the input logic supply (V_A), this assures that this input remains within the input voltage range. The pull-up resistor should go to the output logic supply (V_B) .

Figure 12. Universal Logic Level Shifter



Schematic Diagram







REVISION HISTORY

| CI | hanges from Revision B (March 2013) to Revision C | Page |
|----|--|--------------|
| • | Changed layout of National Data Sheet to TI format | (|

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PACKAGING INFORMATION

| Orderable Device | Status | Package Type | Package Drawing | Pins | Package Qty | Eco Plan | Lead finish/ Ball material | MSL Peak Temp | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|----------|--------------|--------------------|------|----------------|--------------|-------------------------------|--------------------|--------------|-------------------------|---------|
| LM6511IM | OBSOLETE | SOIC | D | 8 | | TBD | Call TI | Call TI | -40 to 85 | LM65 11IM | |
| LM6511IM/NOPB | ACTIVE | SOIC | D | 8 | 95 | RoHS & Green | SN | Level-1-260C-UNLIM | -40 to 85 | LM65 11IM | Samples |
| LM6511IMX/NOPB | ACTIVE | SOIC | D | 8 | 2500 | RoHS & Green | SN | Level-1-260C-UNLIM | -40 to 85 | LM65 11IM | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





| A0 | Dimension designed to accommodate the component width |
|----|---|
| В0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| Device | | Package Drawing | | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|----------------|------|--------------------|---|------|--------------------------|--------------------------|------------|------------|------------|------------|-----------|------------------|
| LM6511IMX/NOPB | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.5 | 5.4 | 2.0 | 8.0 | 12.0 | Q1 |

PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

| | Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|---|----------------|--------------|-----------------|------|------|-------------|------------|-------------|
| I | LM6511IMX/NOPB | SOIC | D | 8 | 2500 | 367.0 | 367.0 | 35.0 |

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

| Device | Package Name | Package Type | Pins | SPQ | L (mm) | W (mm) | T (µm) | B (mm) |
|---------------|--------------|--------------|------|-----|--------|--------|--------|--------|
| LM6511IM/NOPB | D | SOIC | 8 | 95 | 495 | 8 | 4064 | 3.05 |



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES:

- 1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
- 4. This dimension does not include interlead flash.
- 5. Reference JEDEC registration MS-012, variation AA.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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